



WAC2016

World Adhesive & Sealant Conference
世界接着剤・シーリング材会議

Creating Tomorrow ~Environment・Creation・Evolution~
明日を創る ~環境・創造・進化~

October 25-28, 2016

Venue : Shinagawa Prince Hotel, Tokyo, Japan

Message from the President

The World Adhesive & Sealant Conference (WAC) is held every four years, alternating among America, Europe, and Asia, to discuss various subjects related to adhesives and sealants. This time round, it will be held in Asia, and the host country will be Japan, which chairs the Asia Regional Adhesive Council (ARAC). This will be the second time for the Japan Adhesive Industry Association to host the event, following the 4th WAC that was held in Kyoto in 1992.

The world's adhesive industry has achieved remarkable development. The issue with which we are faced, such as environmental problems, legislative controls, and raw material supply problems, are becoming increasingly complicated and globalized. WAC2016 is an international conference that aims to gather not only manufacturers of adhesives and sealants but also suppliers of raw materials, equipment manufacturers, and sales persons together in one place. I believe it is highly significant for the development of the industry that WAC2016 participants take this opportunity to discuss topics in common and see them in a new light.

We look forward to wide participation from the world over. It is our wish that all participants deepen exchanges with one another and seize opportunities for new development at the Conference, and that the four-day conference be a highly productive one. We also hope that all participants will enjoy their stay in exciting and exotic Tokyo to the fullest.

I hope to see you in Tokyo!

Takayuki Nogawa
Chairman of ARAC

President of Japan Adhesive Industry Association
and the President of Nogawa Chemical Co., Ltd.



Organized by Asia Regional Adhesive Council / Japan Adhesive Industry Association

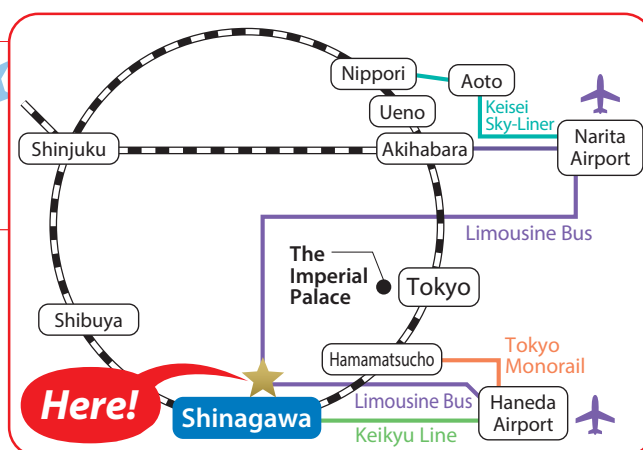
Co-organized by China Adhesives and Tape Industry Association
Korea Adhesive Industry Association
Taiwan Synthetic Resins & Adhesives Industrial Association
The Adhesive and Sealant Council, Inc.
The Association of the European Adhesives & Sealant Industry

► Access

Shinagawa Prince Hotel is only a two-minute walk from Shinagawa Station.

It takes 45 minutes by the limousine bus from Haneda Airport to the hotel.

Venue : Shinagawa Prince Hotel



► Registration Fees

Early	JPY 100,000
Regular	JPY 120,000
Accompanying Persons	JPY 60,000
Chairmen, Speakers	JPY 80,000
Students	JPY 15,000
ONLY Exhibition	For Free

Early and Regular registration include: Admission to all programs, exhibition, all meals including parties, coffee breaks and conference bag.

Accompanying Persons registration includes: All meals including parties, exhibition, coffee breaks and spouse programs.

Students registration includes: Admission to all programs, exhibition, and lunch.

► Important Dates(tentative)

- 1) **Call for Papers** October 1st, 2015 - in the end of January, 2016 *
- 2) **Early Registration** February 1st, 2016 - in the end of June, 2016
- 3) **Regular Registration** Early in July - in the middle of September, 2016

*Notification of acceptance will be made to the authors early in April, 2016.

This information is subject to change. Please check the latest information on the website above.

► Schedule

● 25 Oct 2016

14:00-17:00	IAH Meeting
17:30-20:00	IAH Dinner

● 26 Oct 2016

9:00-	Opening Address
9:10-	Invited Memorable Speech
11:30-15:00	Plenary Lecture
15:00-16:00	Subcommittee meeting
18:00-	Welcome Party

● 27 Oct 2016

9:30-11:00	Subcommittee meeting
11:00-11:30	Coffee Break
11:30-18:00	Subcommittee meeting
18:00-20:30	Gala Dinner

● 28 Oct 2016

9:00-12:00	Subcommittee meeting
12:00-14:30	Farewell Party

*Exhibition is held at Shinagawa Prince Hotel during the Conference.

<Theme of Subcommittee meeting>

- ① Environment ② Creation ③ Evolution

► Secretariat Office

WAC2016 Secretariat Office

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